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2021 - October  
**Guidance for the  
Development and  
Implementation of a  
White Plague Control Plan  
(WPCP)**

*A White Paper Report Developed by IPC*



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IPC-WP-114A

# Guidance for the Development and Implementation of a White Plague Control Plan (WPCP)

Developed by the Wire Harness Design Task Group (7-31k)  
of the Product Assurance Committee (7-30) of IPC

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Users of this publication are encouraged to participate in the  
development of future revisions.

Contact:

IPC  
3000 Lakeside Drive, Suite 105 N  
Bannockburn, Illinois  
60015-1249  
Tel 847 615.7100  
Fax 847 615.7105

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---

### Product Assurance Committee

#### Chair

Robert W. Cooke  
NASA Johnson Space Center

#### Vice-Chair

Debbie Wade  
Advanced Rework Technology

### Wire Harness Design Task Group

#### Chair

Robert W. Cooke  
NASA Johnson Space Center

#### Vice-Chair

Sean Keating  
Amphenol Ltd (UK)

### Technical Liaison of the IPC Board of Directors

#### Bob Neves

Microtek (Changzhou) Laboratories

---

### Members of Wire Harness Design Task Group

Dominik Alder  
Lockheed Martin Corporation

Anisha Ankush  
ATRON Group LLC

Michael Baker

Vincent Barone  
Panduit Corporation

Geza Batiz  
Toro Co.

Cathy Becker  
JC Manufacturing

James Blanche  
NASA Marshall Space Flight Center

Gerald Bogert  
Bechtel Plant Machinery, Inc.

Alvin Boutte  
NASA Goddard Space Flight Center

Bud Bowen  
Winchester Interconnect

Lance Brack  
Raytheon Missile Systems

Thomas Carle  
Ball Aerospace &  
Technologies Corp.

Zhiman Chen  
Zhuzhou CRRC Times  
Electric Co., LTD.

Thomas Cleere

Robert Cooke  
NASA Johnson Space Center

Stephen Cooke  
Electrical Components International

Miguel Dominguez  
Continental Temic SA de CV

Bill Downton  
Cirris Systems Corporation

Caroline Ehlinger  
Collins Aerospace

Chris Fitzgerald  
NASA Goddard Space Flight Center

Robert Fornefeld  
STI Electronics, Inc.

Daniel Foster  
Missile Defense Agency (MDA)

B.J. Franco  
Honeywell Aerospace

Mahendra Gandhi  
Northrop Grumman Space Systems

Matt Garrett  
Microsemi

Constantino Gonzalez  
ACME Training & Consulting

William Graver  
NTS - Baltimore

Dave Harrell  
Viasat Inc.

Eric Harenburg  
Boeing Company

Rick Hawthorne  
Technical Training Center

Gaston Hidalgo  
Toyota Motor North America

David Hillman  
Collins Aerospace

Shelley Holt  
L3Harris Communications

Ife Hsu  
Intel Corporation

Paula Jackson  
Raytheon UK

Kathy Johnston

Lawrence Joy

Joseph Kane  
BAE Systems

Sean Keating  
Amphenol Ltd (UK)

Jason Keeping  
Celestica International L.P.

Russell Kido  
Practical Components Inc.

---

Rebekah Kovarik Lockheed Martin	Bob Potysman ATRON Group LLC	Stephen Tisdale Tisdale Environmental Consulting LLC
Vijay Kumar Lockheed Martin Missiles & Fire Control	Sue Powers-Hartman Killdeer Mountain Manufacturing, Inc.	Jonathon Vermillion Ball Aerospace & Technologies Corp.
Leo Lambert EPTAC Corporation	Ray Prasad Ray Prasad Consultancy Group	Daniel Versluis HYTEK
Theodore Laser L3Harris Communications	ErViik Quam Uson LP	Debie Vorwald Collins Aerospace
Evan Levy	Edward Rios Motorola Solutions	Debbie Wade Advanced Rework Technology
John Mastorides Honeywell Aerospace	Richard Rumas Honeywell Canada	Schuyler Williams Lockheed Martin Missiles & Fire Control
Garry McGuire NASA Marshall Space Flight Center	Tammy Sargent Collins Aerospace	Alan Young Jet Propulsion Laboratory
Randy McNutt Northrop Grumman Aerospace Systems	Martin Scionti Raytheon Vision Systems	Style Yuan Winchester Electronics (Suzhou) Co., Ltd.
Roger Miedico Raytheon Company	Darrell Sensing BAE Systems	Jack Zhu Veoneer China CO.,LTD
Brett Miller USA Harness, Inc.	Jose Servin Olivares Vitesco Technologies	Yaakov Zissman Elta Systems Ltd.
George Millman Raytheon Missile Systems	Gilbert Shelby Raytheon Systems Company	Paul Zutter U.S. Army Aviation & Missile Command
Fernando Moreno Cesar-Scott, Inc.	Kim Souva Kearfott Corporation	
Mark Northrup Raytheon Missile Systems	Toshiyasu Takei Japan Unix Co., Ltd.	
Agnieszka Ozarowski BAE Systems	Bob Teegarden Honeywell International - Torrance	

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# Guidance for the Development and Implementation of a White Plague Control Plan (WPCP)

## TECHNICAL BACKGROUND

During the manufacturing of fluoropolymer-insulated electrical wires and cables made with tin-coated, silver-coated, or nickel-coated conductors of copper or copper alloy, the extrusion of fluorocarbon resin occurs at a temperature high enough that oxidative degradation of the polymer will occur, resulting in the evolution or outgassing of a number of materials, including carbonyl fluoride ( $\text{COF}_2$ ), an extremely reactive compound. This outgassing from the insulation jacket is both internal (to the wire strand/cable bundle) and external (to the surrounding environment).

**Chemical Reaction** – In the presence of trace atmospheric moisture (e.g., humidity), the carbonyl-difluoride hydrolyzes to generate carbon dioxide ( $\text{CO}_2$ ) and hydrogen fluoride (HF). The hydrogen fluoride (HF) will then hydrate to form concentrated hydrofluoric acid (HF aq), which is a corrosive agent that reacts with metal and metal oxides.

**Scavenger/Dopant** – Antimony oxide ( $\text{Sb}_2\text{O}_3$ ) is known for its ability to scavenge the decomposed HF, preventing wires from the corrosive attack by the decomposed HF, and wire manufacturers heavily dope the fluoropolymer insulation with antimony oxide to reduce the amount of outgassing. However, while the amount of antimony oxide in the insulation might be able to reduce the amount of outgassing and the resultant corrosion in the short term, outgassing and corrosion would eventually occur after the antimony oxide's scavenging capacity is exhausted/overwhelmed.

**ETFE (Tefzel™)** – While fluorine outgassing is a concern for all fluoropolymer insulations, ethylene tetrafluoroethylene (ETFE) and cross-linked ethylene tetrafluoroethylene (XL-ETFE) have been reported to have a higher evolution rate, possibly due to the blending and extrusion processes typically used for this polymer.

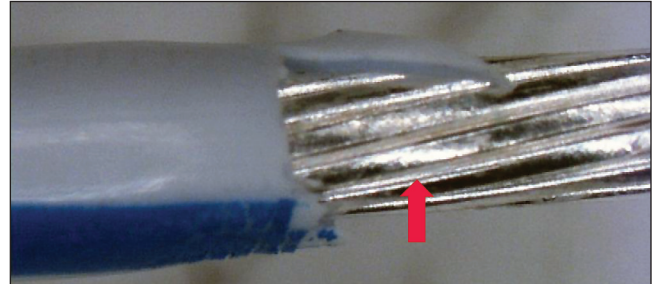
## 1 GENERAL REQUIREMENTS

**1.1 Scope** This document introduces design concepts, guidelines, procedures, practices, process attributes, and recommendations for the control and mitigation of performance and reliability risks associated with the use of fluoropolymer-insulated wire and cable in the manufacture of electrical and electronic assemblies, including optical and metallic cable and wiring harness assemblies, and elements thereof.

**1.2 Purpose** The intent of this document is to provide guidelines and a template for the development and implementation of a White Plague Control Plan (WPCP).

For purposes of this document:

- The Designer is the design agent for the User.
- The User is the individual, organization, company, contractually designated authority, or agency responsible for the procurement or design of electrical / electronic / electromechanical (EEE) hardware and having the authority to define the class of equipment and any variation or restrictions to the requirements of this document (e.g., the originator / custodian of the contract detailing these requirements). The User is considered the Design Authority.
- The Supplier is considered the individual, organization, or company which provides the Manufacturer (assembler) components (e.g., electrical, electronic, electromechanical, mechanical, printed boards, etc.), and/or materials (e.g., solder, flux, cleaning agents, etc.).
- The Manufacturer is considered the entity that provides a service or product to the User.



**Figure 1-1 White Plague (Fluorine Attack)**

Note white frosted section on silver coating

(Photo Courtesy of NASA)